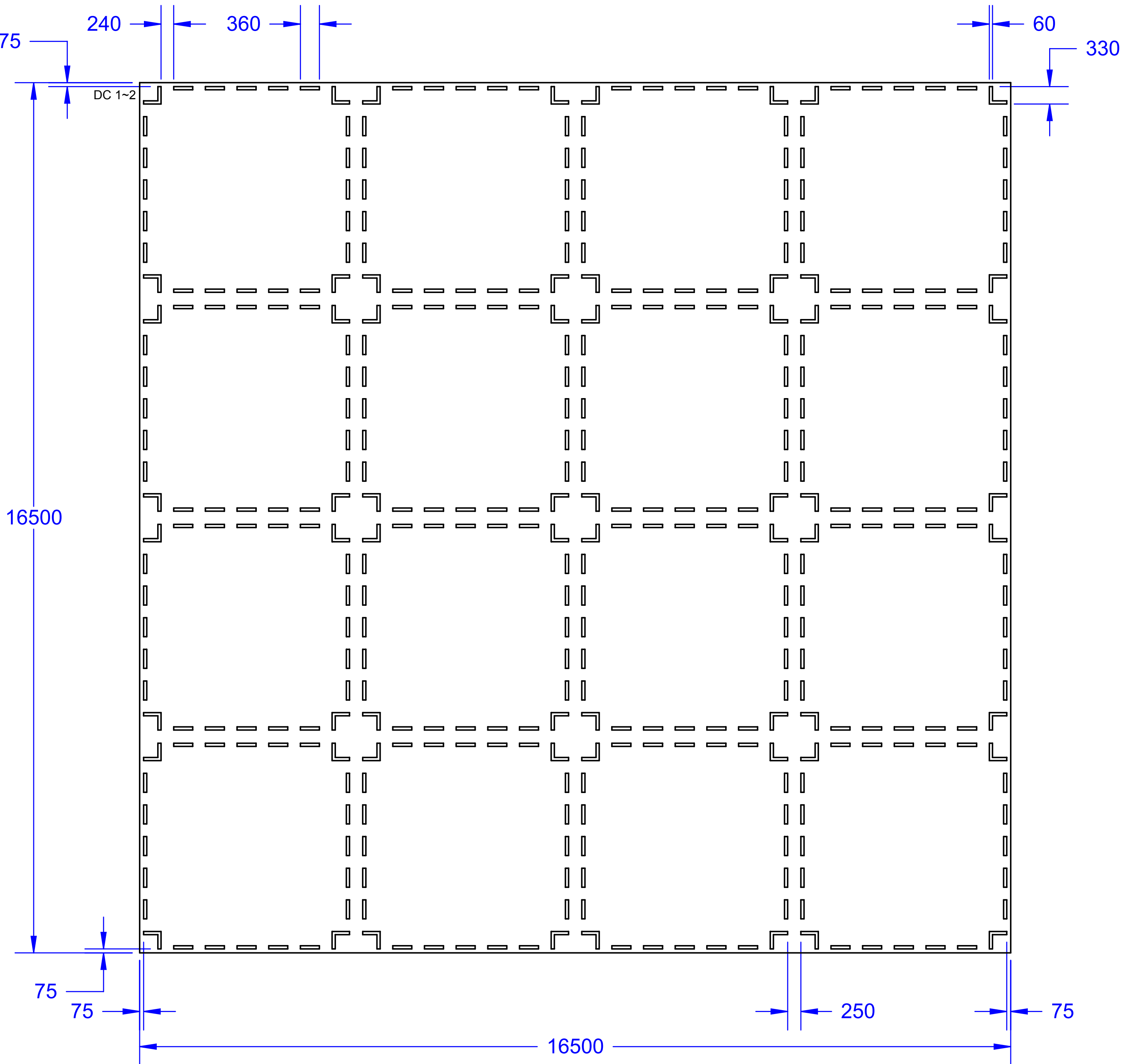
DAISY CHAIN TEST DIE
WIRE BONDABLE
SHOWN WITH CENTER PADS



Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250µm ~ 725µm.
3. METALLIZATION 1.0µm ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.

APPROVALS		DATE	TopLine®			
DRAWN	T.Au	03/15/14				
ENG	M. Hart	03/15/14	TITLE	DAISY CHAIN TEST DIE TD108 16.5 x 16.5MM		
MFG						
QA			SCALE 9:1	SIZE A	DRAWING NO. 154108	REV A
CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 2	

PERIMETER PAD TEST DIE
DAISY CHAIN
SHOWN WITHOUT CENTER PADS FOR CLARITY

240 360 60
75 330

215~216 213~214 211~212 209~210 207~208 205~206 203~204 201~202 199~200 197~198 195~196 193~194 191~192 189~190 187~188 185~186 183~184 181~182 179~180 177~178 175~176 173~174 171~172 169~170 167~168 165~166

DC 1~2
3~4
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9~10
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43~44
45~46
47~48
49~50
51~52
53~54
55~56

16500

163~164
161~162
159~160
157~158
155~156
153~154
151~152
149~150
147~148
145~146
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141~142
139~140
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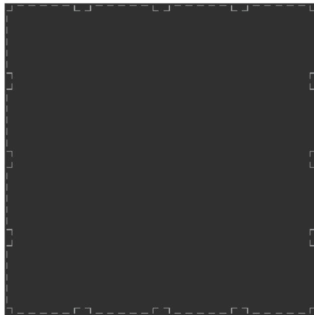
113~114
111~112
109~110

57~58 59~60 61~62 63~64 65~66 67~68 69~70 71~72 73~74 75~76 77~78 79~80 81~82 83~84 85~86 87~88 89~90 91~92 93~94 95~96 97~98 99~100 101~102 103~104 105~106 107~108

75 75 250 75

16500



SCALE 2.5:1

Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250µm ~ 725µm.
3. METALLIZATION 1.0µm ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.

DIMENSION IN MICRONS
1.0mm = 1000µm

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MFG						
QA			SCALE 9:1	SIZE A	DRAWING NO. 154108	REV A
CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 2 OF 2	